	Application No.	Applicant(s)
Notic of Allowability	10/630,570	LEE ET AL.
	Examiner	Art Unit
	Asok K. Sarkar	2829
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.		
1. X This communication is responsive to Application filed 7/29/2003.		
2. The allowed claim(s) is/are 1-14.		
3. 🔀 The drawings filed on 29 July 2003 are accepted by the Examiner.		
4.		
Attachment(s)  1. ☑ Notice of References Cited (PTO-892)  2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)  3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 7/29/2003  4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material	6. ☐ Interview Summary Paper No./Mail Da 08), 7. ☐ Examiner's Amendr	te

## **DETAILED ACTION**

## Allowable Subject Matter

- 1. Claims 1 14 are allowed.
- 2. The following is an examiner's statement of reasons for allowance:

Claims 1 – 13 recite, inter alia, a method of forming a silicide film of a semiconductor device comprising performing a radio frequency etching process ex-situ that removes impurities from the conductive pattern and the conduction region on the substrate and that uniformly planarizes a surface of the conduction region; and performing a cleaning process that removes residues generated during the radio frequency etching process from the conductive pattern and the conduction region. Although, it is well known to perform a cleaning process to remove residues generated by the etching process, the claimed process of cleaning the residue after ex-situ radio frequency etching process to remove impurities from the conductive pattern and the conduction region on the substrate and that uniformly planarizes the surface of the conduction region appears novel. Nutley, US 2002/0146897 teaches a similar process but fails to teach the step of removing residues generated during the radio frequency etching process. Additionally, the art of record does not disclose or anticipate the above limitation in combination with other claim elements nor would it be obvious to modify the art of record so as to form a device including the above limitation.

Claim 14 recites, inter alia, a method of forming a silicide film of a semiconductor device comprising performing a radio frequency etching process ex-situ on a resultant structure on the substrate that provides silicon in the source/drain regions having a

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uniformly amorphous phase and performing a cleaning process that removes residues generated during the radio frequency etching process. Although, it is well known to perform a cleaning process to remove residues generated by the etching process, the claimed process of cleaning the residue after ex-situ radio frequency etching process of the source and drain regions appears novel. Nutley, US 2002/0146897 teaches a similar process but fails to teach the step of removing residues generated during the radio frequency etching process. Additionally, the art of record does not disclose or anticipate the above limitation in combination with other claim elements nor would it be obvious to modify the art of record so as to form a device including the above limitation.

## Conclusion

- 3. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."
- 4. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Kamal, US 6,303,503 teaches a method of forming silicide employing a sputter etch process.
- 5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Asok K. Sarkar whose telephone number is 571 272 1970. The examiner can normally be reached on Monday Friday (8 AM- 5 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571 272 1957. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

6. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Asok K. Sarkar May 11, 2004

Patent Examiner

Parish. Javide Davish. Farneke Primary Exam 5/14/04